L Number	Hits	Search Text	DB	Time stamp
-	163	(IC adj package).ti.	USPAT; US-PGPUB	2003/03/22 17:27
-	216	(IC adj package).ti.	USPAT; US-PGPUB	2003/03/22 11:05
-	16	((IC adj package).ti.) and 324/$.ccls.	USPAT; US-PGPUB	2003/03/22 11:15
-	2	(((IC adj package).ti.) and 439/$.ccls.) and bond	USPAT; US-PGPUB	2003/03/22 11:14
-	1	(((IC adj package).ti.) and 324/$.ccls.) and bond	USPAT; US-PGPUB	2003/03/22 11:14
-	432	324/$.ccls. and package and adhesive and chip	USPAT; US-PGPUB	2003/03/22 11:15
-	280	324/$.ccls. and package and adhesive and chip and bond	USPAT; US-PGPUB	2003/03/22 11:15
-	19	324/$.ccls. and package and adhesive and chip and bond and indium	USPAT; US-PGPUB	2003/03/22 12:42
-	36	((IC adj package).ti.) and 439/$.ccls.	USPAT; US-PGPUB	2003/03/22 11:49
-	5166	(package near comprising).clm.	USPAT; US-PGPUB	2003/03/22 11:50
-	0	((package near comprising).clm.) and conductive near2 adheshive	USPAT; US-PGPUB	2003/03/22 11:53
-	1	((package near comprising).clm.) and ECA	USPAT; US-PGPUB	2003/03/22 11:51
-	55	((package near comprising).clm.) and 324/$.ccls.	USPAT; US-PGPUB	2003/03/22 11:52
-	0	(((package near comprising).clm.) and 324/$.ccls.) and adheshive	USPAT; US-PGPUB	2003/03/22 11:52
-	194	((package near comprising).clm.) and conductive near2 adhesive	USPAT; US-PGPUB	2003/03/22 11:52
-	17	(((package near comprising).clm.) and 324/$.ccls.) and adhesive	USPAT; US-PGPUB	2003/03/22 11:53
-	194	((package near comprising).clm.) and conductive near2 adhesive	USPAT; US-PGPUB	2003/03/22 12:24
-	3	(((package near comprising).clm.) and conductive near2 adhesive) and 324/$.ccls.	USPAT; US-PGPUB	2003/03/22 11:57
-	104	(((package near comprising).clm.) and conductive near2 adhesive) and 257/$.ccls.	USPAT; US-PGPUB	2003/03/22 11:58
-	94	((((package near comprising).clm.) and conductive near2 adhesive) and 257/$.ccls.) and bond$	USPAT; US-PGPUB	2003/03/22 12:00
-	62	((((package near comprising).clm.) and conductive near2 adhesive) and 257/$.ccls.) and wire adj bond$	USPAT; US-PGPUB	2003/03/22 12:03
-	41	(((((package near comprising).clm.) and conductive near2 adhesive) and 257/$.ccls.) and wire adj bond$) and (gold indium)	USPAT; US-PGPUB	2003/03/22 12:22
-	2	(((((package near comprising).clm.) and conductive near2 adhesive) and 257/$.ccls.) and wire adj bond$) and indium	USPAT; US-PGPUB	2003/03/22 12:22
-	3	((package near comprising).clm.) and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:24
-	3	324/$.ccls. and package and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:55
-	2	439/$.ccls. and package and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:55
-	23	257/$.ccls. and package and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:55
-	2	"6489178"	USPAT; US-PGPUB	2003/03/22 13:29
-	2	("5151276" | "5897338").PN.	USPAT	2003/03/22 13:29
-	1059	438/118-119.ccls.	USPAT; US-PGPUB	2003/03/22 13:51
-	66	438/118-119.ccls. and indium	USPAT; US-PGPUB	2003/03/22 13:44
-	2	438/118-119.ccls. and adhesive with indium	USPAT; US-PGPUB	2003/03/22 13:44

-	1136	438/106.ccls.	USPAT; US-PGPUB	2003/03/22 13:53
-	2	438/106.ccls. and adhesive with indium	USPAT; US-PGPUB	2003/03/22 13:52
-	1394	438/14-15.ccls.	USPAT; US-PGPUB	2003/03/22 13:57
-	227	438/14-15.ccls. and adhesive	USPAT; US-PGPUB	2003/03/22 13:54
-	1	438/14-15.ccls. and adhesive with indium	USPAT; US-PGPUB	2003/03/22 13:54
-	530	438/15.ccls.	USPAT; US-PGPUB	2003/03/22 13:57
-	224	438/15.ccls. and therm$	USPAT; US-PGPUB	2003/03/22 13:58
-	0	(438/15.ccls. and therm$) and induim	USPAT; US-PGPUB	2003/03/22 13:58
-	16	(438/15.ccls. and therm$) and indium	USPAT; US-PGPUB	2003/03/22 14:10
-	2	(("6251696") or ("5994716")).PN.	USPAT; US-PGPUB	2003/03/22 14:10
-	390	eutectic with indium	USPAT; US-PGPUB	2003/03/22 15:20
-	6	(eutectic with indium) and 324/$.ccls.	USPAT; US-PGPUB	2003/03/22 15:24
-	574	aluminum with boron with beryllium with oxide	USPAT; US-PGPUB	2003/03/22 15:25
-	766	aluminum with boron with beryllium with oxide	USPAT; US-PGPUB	2003/03/22 15:25
-	192	aluminum with boron with beryllium with oxide with ceramic	USPAT; US-PGPUB	2003/03/22 15:26
-	0	(aluminum with boron with beryllium with oxide with ceramic) and 324/$.ccls.	USPAT; US-PGPUB	2003/03/22 15:25
-	23	aluminum with boron with beryllium with oxide with ceramic with substrate	USPAT; US-PGPUB	2003/03/22 15:26
-	31	semiconductor near2 thermal near2 sensor	USPAT; US-PGPUB	2003/03/22 15:56
-	0	(semiconductor near2 thermal near2 sensor) and washer	USPAT; US-PGPUB	2003/03/22 15:57
-	11	(semiconductor near2 thermal near2 sensor) and mount	USPAT; US-PGPUB	2003/03/22 16:44
-	0	(semiconductor near2 thermal near2 sensor) and mount	EPO; JPO; DERWENT; IBM_TDB	2003/03/22 16:44
-	20	semiconductor near2 thermal near2 sensor	EPO; JPO; DERWENT; IBM_TDB	2003/03/22 16:44
-	2	(("6251696") or ("5126813")).PN.	USPAT; US-PGPUB	2003/03/22 17:27
-	1	((("6251696") or ("5126813")).PN.) and size	USPAT; US-PGPUB	2003/03/22 17:28
-	1	((("6251696") or ("5126813")).PN.) and mm	USPAT; US-PGPUB	2003/03/22 17:28